1.6x0.2mm RIGHT ANGLE SMD CHIP LED LAMP

Part Number: KPGA-1602CGC-KA

Green

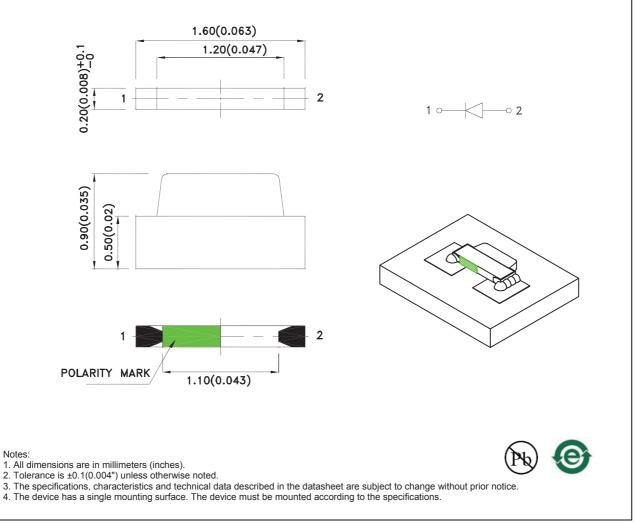
Features

- 1.6mmx0.9mm right angle SMT LED,0.2mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Moisture sensitivity level : level 3.
- Package :2000pcs / reel.
- Tinned pads for improved solderability.
- RoHS compliant.

Package Dimensions

Description

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.



SPEC NO: DSAN1962 APPROVED: WYNEC REV NO: V.1B CHECKED: Allen Liu DATE: AUG/31/2013 DRAWN: Q.M.Chen PAGE: 1 OF 5 ERP: 1203013815

Selection Guide									
Part No.	Dice	Lens Type	@ 20mA		Angle [1]				
			Min.	Тур.	201/2				
KPGA-1602CGC-KA	Green(AlGaInP)	Water Clear	12	30	160 [°] (H) 145 [°] (V)				

Notes:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.
3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	573		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Green	571		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Green	15		nm	I⊧=20mA
VF [2]	Forward Voltage	Green	2.05	2.4	V	IF=20mA
IR	Reverse Current	Green		10	uA	VR=5V

Notes:

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

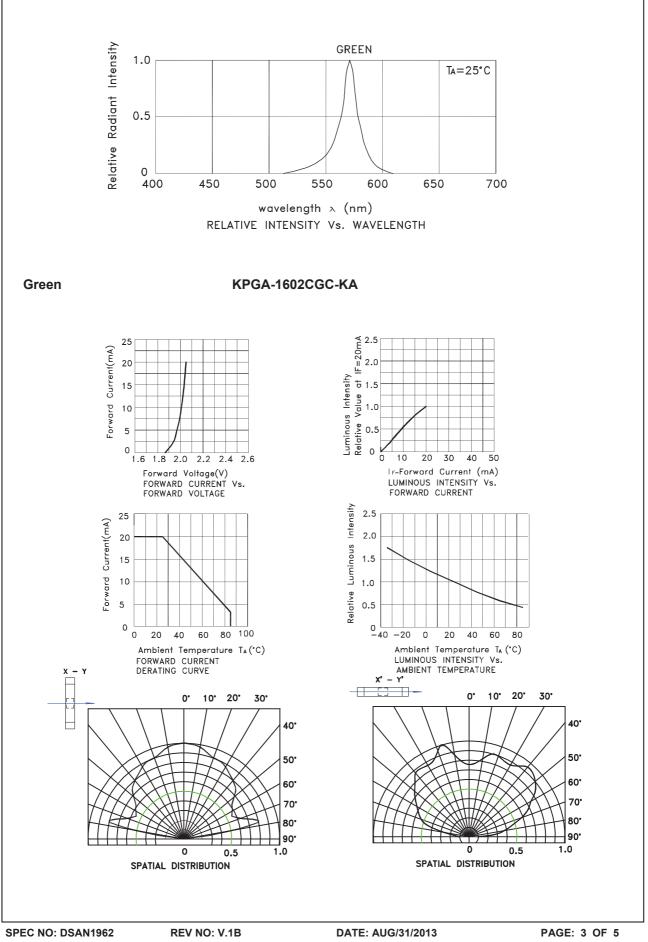
3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units		
Power dissipation	48	mW		
DC Forward Current	20	mA		
Peak Forward Current [1]	100	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +100°C			

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



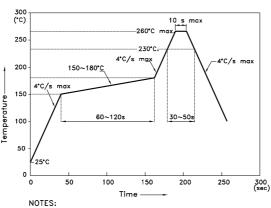
CHECKED: Allen Liu

DATE: AUG/31/2013 DRAWN: Q.M.Chen

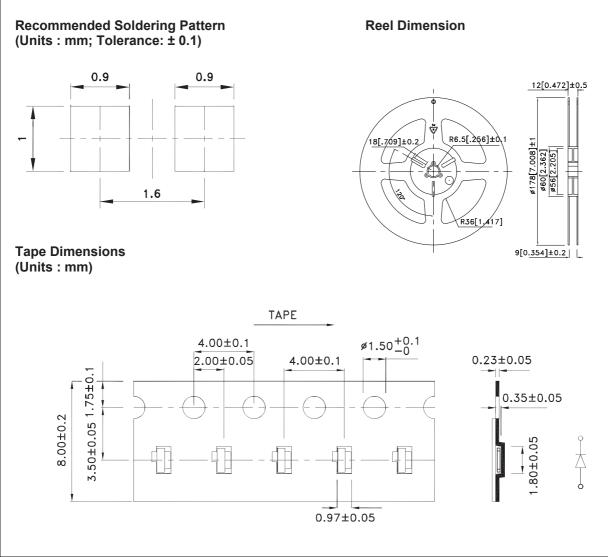
KPGA-1602CGC-KA

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

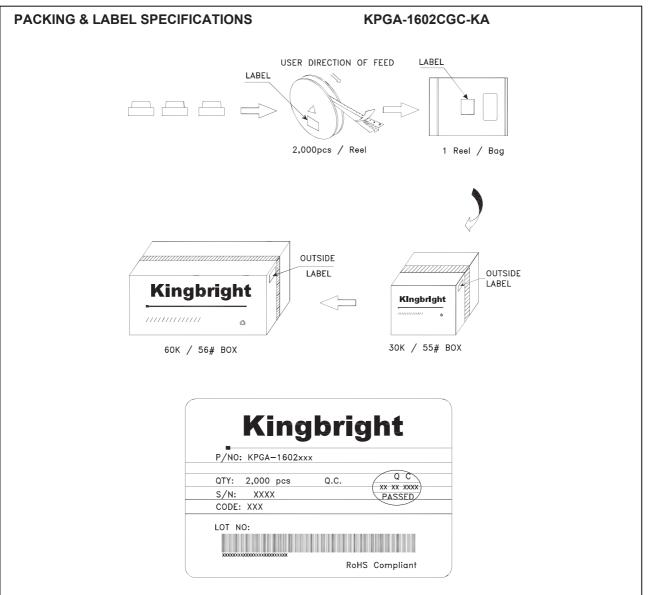
Reflow Soldering Profile For Lead-free SMT Process.



1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.



DATE: AUG/31/2013 DRAWN: Q.M.Chen



Terms and conditions for the usage of this document

- 1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- 2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- 3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
- 4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
- 5. The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright.

6.All design applications should refer to Kingbright application notes available at http://www.kingbright.com/application_notes